

DS3658 Quad High Current Peripheral Driver

Check for Samples: [DS3658](#)

FEATURES

- **Single Saturated Transistor Outputs**
- **Low Standby Power, 10 mW Typical**
- **High Impedance TTL Compatible Inputs**
- **Outputs May Be Tied Together for Increased Current Capacity**
- **High Output Current**
 - 600 mA Per Output
 - 2.4A Per Package
- **No Output Latch-up at 35V**
- **Low Output ON Voltage (350 mV typ @ 600 mA)**
- **High Breakdown Voltage (70V)**
- **Open Collector Outputs**
- **Output Clamp Diodes for Inductive Fly Back Protection**
- **NPN Inputs for Minimal Input Currents (1 μ A Typical)**
- **Low Operating Power**
- **Standard 5V Power Supply**
- **Power Up/Down Protection**
- **Fail Safe Operation**
- **2W Power Package**
- **Pin-for-Pin Compatible with SN75437**

APPLICATIONS

- **Relay Drivers**
- **Lamp Drivers**
- **Solenoid Drivers**
- **Hammer Drivers**
- **Stepping Motor Drivers**
- **Triac Drivers**
- **LED Drivers**
- **High Current, High Voltage Drivers**
- **Level Translators**
- **Fiber Optic LED Drivers**

DESCRIPTION

The DS3658 quad peripheral driver is designed for those applications where low operating power, high breakdown voltage, high output current and low output ON voltage are required. A unique input circuit combines TTL compatibility with high impedance. In fact, its extreme low input current allows it to be driven directly by a CMOS device.

The outputs are capable of sinking 600 mA each and offer a 70V breakdown. However, for inductive loads the output should be clamped to 35V or less to avoid latch-up during turn off (inductive fly back protection—refer to AN-213 '[SNOA610](#)'). An on-chip clamp diode capable of handling 800 mA is provided at each output for this purpose. In addition, the DS3658 incorporates circuitry that specifies glitch-free power up or down operation and a fail-safe feature which puts the output in a high impedance state when the input is open.

The PDIP package is specifically constructed to allow increased power dissipation over conventional packages. The four ground pins are directly connected to the device chip with a special cooper lead frame. When the quad driver is soldered into a PC board, the power rating of the device improves significantly.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

All trademarks are the property of their respective owners.

Connection Diagram

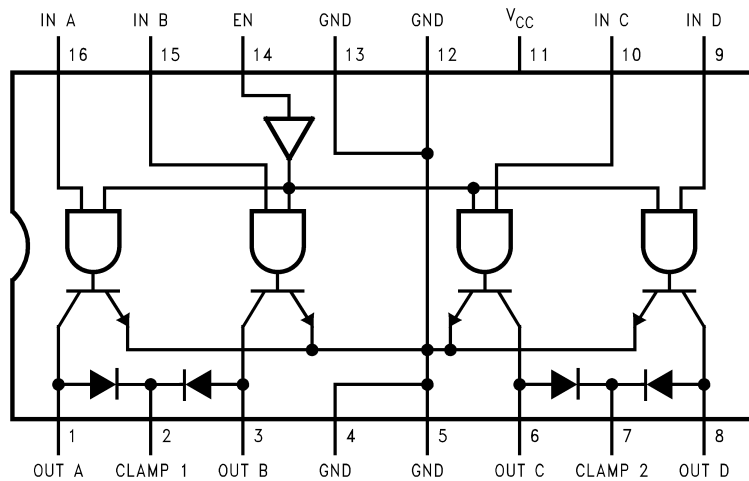


Figure 1. PDIP- Top View
See Package Number NFG0016E



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

Absolute Maximum Ratings ⁽¹⁾⁽²⁾

Supply Voltage	7V
Input Voltage	15V
Output Voltage	70V
Output Current	1.5A
Continuous Power Dissipation @ 25°C Free-Air ⁽³⁾	2075 mW
Storage Temperature Range	-65°C to +150°C
Lead Temperature (Soldering, 4 sec.)	260°C

- (1) "Absolute Maximum Ratings" are those values beyond which the safety of the device cannot be specified. They are not meant to imply that the device should be operated at these limits. [Electrical Characteristics](#) provides conditions for actual device operation.
- (2) If Military/Aerospace specified devices are required, please contact the Texas Instruments Sales Office/ Distributors for availability and specifications.
- (3) For operation over 25° free-air temperature, derate linearly to 1328 mW @ 70°C @ the rate of 16.6 mW/°C.

Operating Conditions

	Min	Max	Units
Supply Voltage	4.75	5.25	V
Ambient Temperature	0	70	°C

Electrical Characteristics⁽¹⁾⁽²⁾

Symbol	Parameter	Conditions	Min	Typ	Max	Units
V _{IH}	Input High Voltage		2.0			V
V _{IL}	Input Low Voltage				0.8	V
I _{IH}	Input High Current	V _{IN} = 5.25V, V _{CC} = 5.25V		1.0	1.0	μA
I _{IL}	Input Low Current	V _{IN} = 0.4V			±10	μA
V _{IK}	Input Clamp Voltage	I _I = -12 mA		-0.8	-1.5	V
V _{OL}	Output Low Voltage	I _L = 300 mA		0.2	0.4	V
		I _L = 600 mA ⁽³⁾		0.35	0.7	V
I _{CEX}	Output Leakage Current	V _{CE} = 70V, V _{IN} = 0.8V			100	μA
V _F	Diode Forward Voltage	I _F = 800 mA		1.0	1.6	V
I _R	Diode Leakage Current	V _R = 70V			100	μA
I _{CC}	Supply Current	All Inputs High		60	85	mA
		All Inputs Low		2	4	mA

- (1) Unless otherwise specified, min/max limits apply across the 0°C to +70°C temperature range and the 4.75V to 5.25V power supply range. All typical values are for T_A = 25°C and V_{CC} = 5.0V.
- (2) All currents into device pins are shown as positive, all currents out of device pins are shown as negative, all voltages are referenced to ground, unless otherwise specified. All values shown as max or min are so classified on absolute value basis.
- (3) All sections of this quad circuit may conduct rated current simultaneously, however, power dissipation averaged over a short interval of time must fall within specified continuous dissipation ratings.

Switching Characteristics⁽¹⁾

Symbol	Parameter	Conditions	Min	Typ	Max	Units
t _{PHL}	Turn On Delay	R _L = 60Ω, V _L = 30V		226	500	ns
t _{PLH}	Turn Off Delay	R _L = 60Ω, V _L = 30V		2430	8000	ns

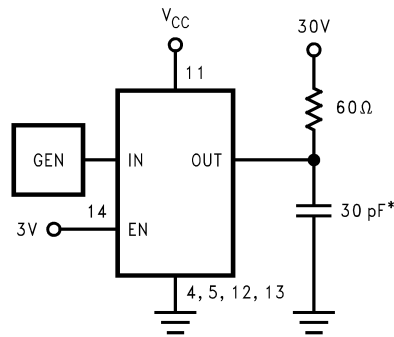
- (1) Unless otherwise specified, min/max limits apply across the 0°C to +70°C temperature range and the 4.75V to 5.25V power supply range. All typical values are for T_A = 25°C and V_{CC} = 5.0V.

Truth Table⁽¹⁾

IN	EN	OUT
H	H	L
L	H	Z
H	L	Z
L	L	Z

- (1) H = High state
L = Low state
Z = High impedance state

AC Test Circuit



*Includes probe and jig capacitance.

Figure 2.

Switching Waveforms

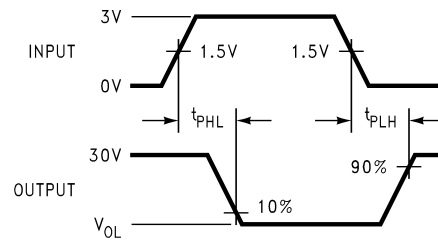
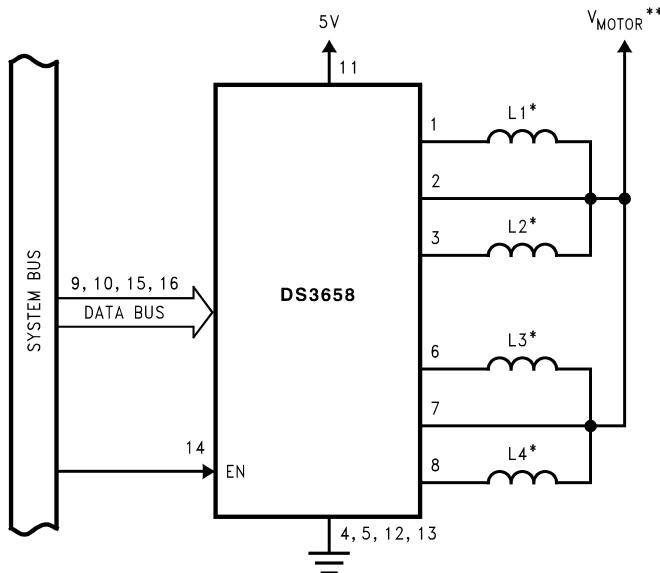


Figure 3.

Typical Applications



*L1, L2, L3, L4 are the windings of a bifilar stepping motor.
 **V_{MOTOR} is the supply voltage of the motor.

Figure 4. Stepping Motor Driver

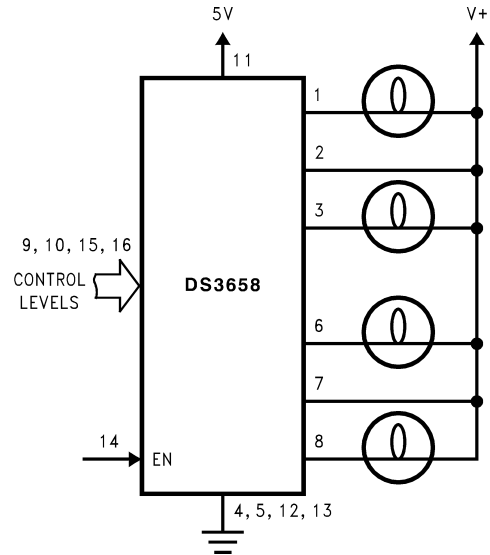


Figure 5. Lamp Driver

REVISION HISTORY

Changes from Revision A (April 2013) to Revision B	Page
• Changed layout of National Data Sheet to TI format	4

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
DS3658N	LIFEBUY	PDIP	NFG	16	25	TBD	Call TI	Call TI	0 to 70	DS3658N	
DS3658N/NOPB	LIFEBUY	PDIP	NFG	16	25	Green (RoHS & no Sb/Br)	CU SN	Level-1-NA-UNLIM	0 to 70	DS3658N	

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

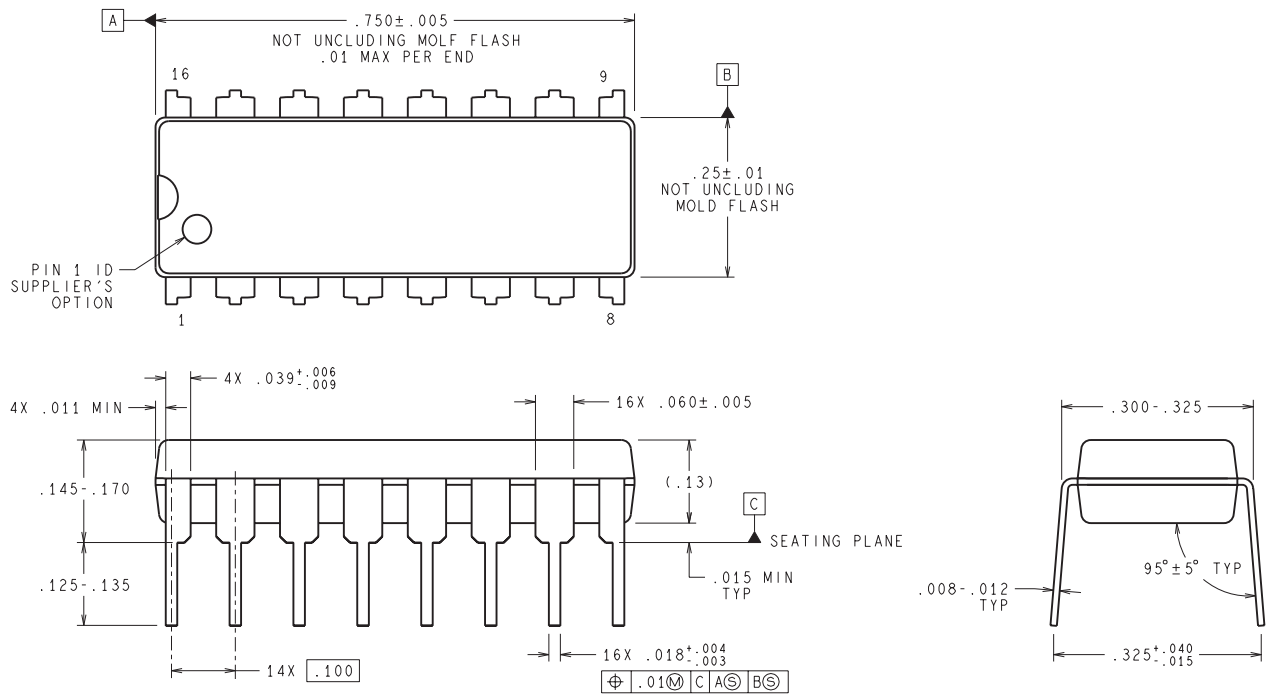
(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

Important Information and Disclaimer:The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

NFG0016E



DIMENSIONS ARE IN INCHES
 DIMENSIONS IN () FOR REFERENCE ONLY

N16E (Rev G)

IMPORTANT NOTICE

Texas Instruments Incorporated (TI) reserves the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete.

TI's published terms of sale for semiconductor products (<http://www.ti.com/sc/docs/stdterms.htm>) apply to the sale of packaged integrated circuit products that TI has qualified and released to market. Additional terms may apply to the use or sale of other types of TI products and services.

Reproduction of significant portions of TI information in TI data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such reproduced documentation. Information of third parties may be subject to additional restrictions. Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyers and others who are developing systems that incorporate TI products (collectively, "Designers") understand and agree that Designers remain responsible for using their independent analysis, evaluation and judgment in designing their applications and that Designers have full and exclusive responsibility to assure the safety of Designers' applications and compliance of their applications (and of all TI products used in or for Designers' applications) with all applicable regulations, laws and other applicable requirements. Designer represents that, with respect to their applications, Designer has all the necessary expertise to create and implement safeguards that (1) anticipate dangerous consequences of failures, (2) monitor failures and their consequences, and (3) lessen the likelihood of failures that might cause harm and take appropriate actions. Designer agrees that prior to using or distributing any applications that include TI products, Designer will thoroughly test such applications and the functionality of such TI products as used in such applications.

TI's provision of technical, application or other design advice, quality characterization, reliability data or other services or information, including, but not limited to, reference designs and materials relating to evaluation modules, (collectively, "TI Resources") are intended to assist designers who are developing applications that incorporate TI products; by downloading, accessing or using TI Resources in any way, Designer (individually or, if Designer is acting on behalf of a company, Designer's company) agrees to use any particular TI Resource solely for this purpose and subject to the terms of this Notice.

TI's provision of TI Resources does not expand or otherwise alter TI's applicable published warranties or warranty disclaimers for TI products, and no additional obligations or liabilities arise from TI providing such TI Resources. TI reserves the right to make corrections, enhancements, improvements and other changes to its TI Resources. TI has not conducted any testing other than that specifically described in the published documentation for a particular TI Resource.

Designer is authorized to use, copy and modify any individual TI Resource only in connection with the development of applications that include the TI product(s) identified in such TI Resource. NO OTHER LICENSE, EXPRESS OR IMPLIED, BY ESTOPPEL OR OTHERWISE TO ANY OTHER TI INTELLECTUAL PROPERTY RIGHT, AND NO LICENSE TO ANY TECHNOLOGY OR INTELLECTUAL PROPERTY RIGHT OF TI OR ANY THIRD PARTY IS GRANTED HEREIN, including but not limited to any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information regarding or referencing third-party products or services does not constitute a license to use such products or services, or a warranty or endorsement thereof. Use of TI Resources may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

TI RESOURCES ARE PROVIDED "AS IS" AND WITH ALL FAULTS. TI DISCLAIMS ALL OTHER WARRANTIES OR REPRESENTATIONS, EXPRESS OR IMPLIED, REGARDING RESOURCES OR USE THEREOF, INCLUDING BUT NOT LIMITED TO ACCURACY OR COMPLETENESS, TITLE, ANY EPIDEMIC FAILURE WARRANTY AND ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE, AND NON-INFRINGEMENT OF ANY THIRD PARTY INTELLECTUAL PROPERTY RIGHTS. TI SHALL NOT BE LIABLE FOR AND SHALL NOT DEFEND OR INDEMNIFY DESIGNER AGAINST ANY CLAIM, INCLUDING BUT NOT LIMITED TO ANY INFRINGEMENT CLAIM THAT RELATES TO OR IS BASED ON ANY COMBINATION OF PRODUCTS EVEN IF DESCRIBED IN TI RESOURCES OR OTHERWISE. IN NO EVENT SHALL TI BE LIABLE FOR ANY ACTUAL, DIRECT, SPECIAL, COLLATERAL, INDIRECT, PUNITIVE, INCIDENTAL, CONSEQUENTIAL OR EXEMPLARY DAMAGES IN CONNECTION WITH OR ARISING OUT OF TI RESOURCES OR USE THEREOF, AND REGARDLESS OF WHETHER TI HAS BEEN ADVISED OF THE POSSIBILITY OF SUCH DAMAGES.

Unless TI has explicitly designated an individual product as meeting the requirements of a particular industry standard (e.g., ISO/TS 16949 and ISO 26262), TI is not responsible for any failure to meet such industry standard requirements.

Where TI specifically promotes products as facilitating functional safety or as compliant with industry functional safety standards, such products are intended to help enable customers to design and create their own applications that meet applicable functional safety standards and requirements. Using products in an application does not by itself establish any safety features in the application. Designers must ensure compliance with safety-related requirements and standards applicable to their applications. Designer may not use any TI products in life-critical medical equipment unless authorized officers of the parties have executed a special contract specifically governing such use. Life-critical medical equipment is medical equipment where failure of such equipment would cause serious bodily injury or death (e.g., life support, pacemakers, defibrillators, heart pumps, neurostimulators, and implantables). Such equipment includes, without limitation, all medical devices identified by the U.S. Food and Drug Administration as Class III devices and equivalent classifications outside the U.S.

TI may expressly designate certain products as completing a particular qualification (e.g., Q100, Military Grade, or Enhanced Product). Designers agree that it has the necessary expertise to select the product with the appropriate qualification designation for their applications and that proper product selection is at Designers' own risk. Designers are solely responsible for compliance with all legal and regulatory requirements in connection with such selection.

Designer will fully indemnify TI and its representatives against any damages, costs, losses, and/or liabilities arising out of Designer's non-compliance with the terms and provisions of this Notice.